Features

- 5050 package (5.0 x 5.4 x 1.6mm) top-mount SMD LED
- High brightness output
- AlInGaP and InGaN chip technology
- Compact package size
- High reliability performance
- Clear lens configuration

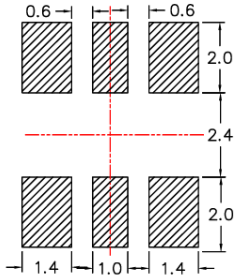
Applications

- Consumer electronics
- Light pipe application
- Automobile aftermarket
- Industrial equipment

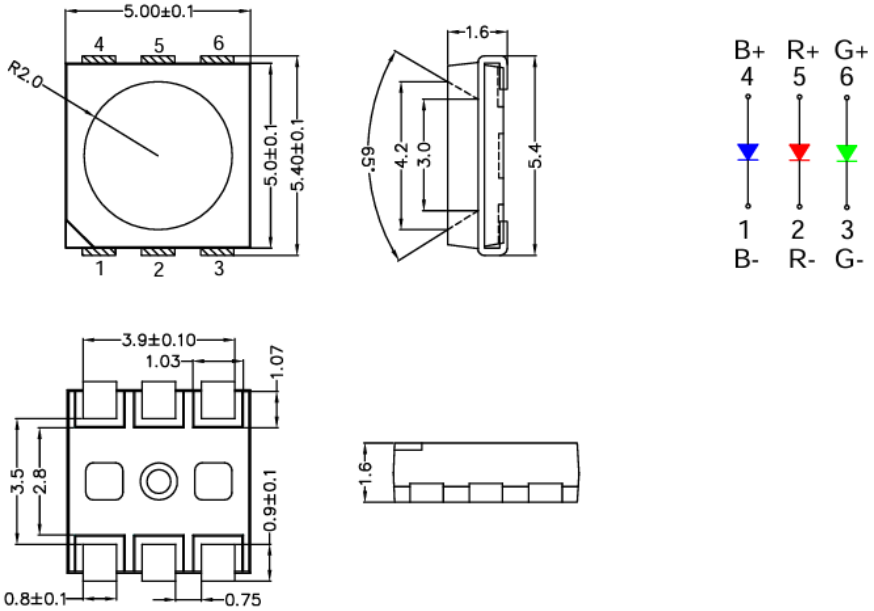
Description

The IN-P55TATRGB is compact RGB 5050 PLCC package with versatile design capabilities. It is a PLCC type LED which can be used in various applications.

Recommended Solder Pattern



Package Dimensions in mm



Notes.
1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise noted

Absolute Maximum Rating T_A = 25℃ (Note)

Product	Emission Color	P_d (mW)	I_F (mA)	I_{FP}* (mA)	V_R (V)	T_{OP} (°C)	T_{ST} (°C)
IN-P55TATRGB	Red	60	25	100	5	-40°C~+80°C	-40°C~+85°C
	Green	85	25	100	5		
	Blue	85	25	100	5		

Note
1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

Electrical Characteristics T_A = 25℃ (Note)

Product	Emission Color	I_F(mA)	V_F(V)		λ(nm)			Viewing Angle (°)	IV(mcd)
			min	max	λ_D	λ_P	△λ	$2\theta_{1/2}$	typ.
IN-P55TATRGB	Red	20	1.6	2.4	624	632	20	120	900
	Green	20	2.8	3.4	520	525	35	120	1800
	Blue	20	2.8	3.4	468	470	25	120	600

Note
1. Performance guaranteed only under conditions listed in above tables.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.
If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

Luminous Intensity (mcd) Bin

Color	Bin Code	Spec. Range
Red	B1	600-700 mcd
	B2	700-800 mcd
	B3	800-900 mcd
	B4	900-1000 mcd
	B5	1000-1100 mcd
	B6	1100-1200 mcd
Green	E1	1500-1600 mcd
	E2	1600-1700 mcd
	E3	1700-1800 mcd
	E4	1800-1900 mcd
	E5	1900-2000 mcd
	E6	2000-2100 mcd
Blue	H1	300-400 mcd
	H2	400-500 mcd
	H3	500-600 mcd
	H4	600-700 mcd
	H5	700-800 mcd
	H6	800-900 mcd

@20mA / Ta=25^{O} C, Measurement Accuracy: ±10%

Dominant Wavelength (nm) Bin

Color	Bin Code	Spec. Range
Red	A1	620-625 nm
	A2	625-630 nm
	A3	630-635 nm
Green	D1	520-525 nm
	D2	525-530 nm
	D3	530-535 nm
Blue	G1	460-465 nm
	G2	465-470 nm
	G3	470-475 nm

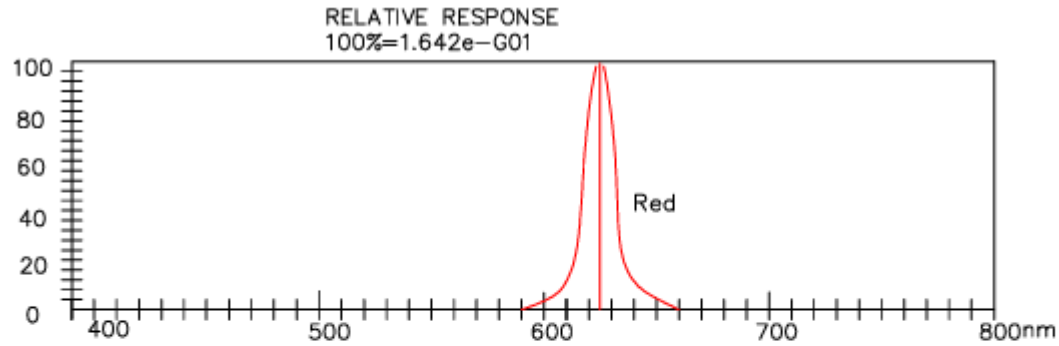
@20mA / Ta=25^{O} C, Measurement Accuracy: ±1.0nm

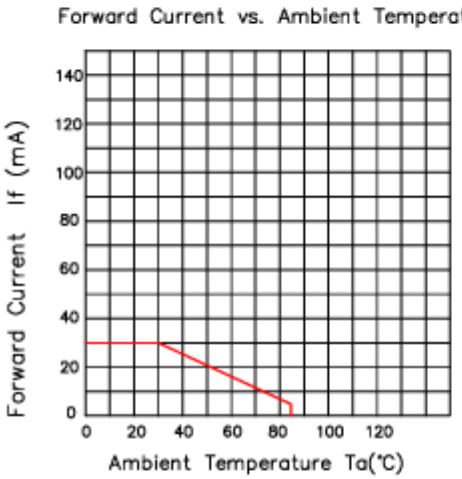
Forward Voltage (V) Bin

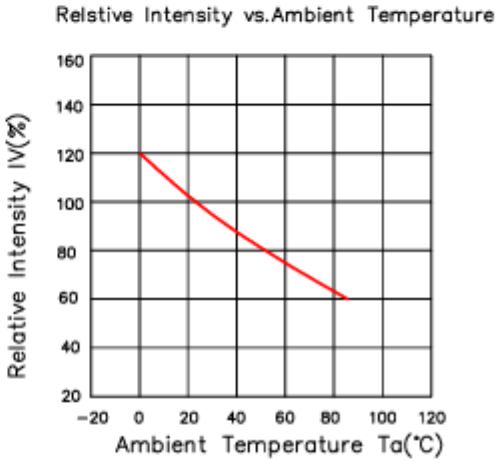
Color	Bin Code	Spec. Range
Red	C0	1.8-2.0 V
	C1	2.0-2.2 V
	C2	2.2-2.4 V
Green	F1	2.8-3.0 V
	F2	3.0-3.2 V
	F3	3.2-3.4 V
Blue	V1	2.8-3.0 V
	V2	3.0-3.2 V
	V3	3.2-3.4 V

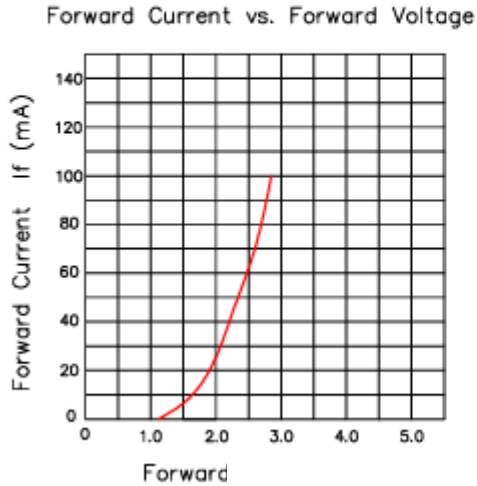
@20mA / Ta=25^{O} C, Measurement Accuracy: ±0.1V

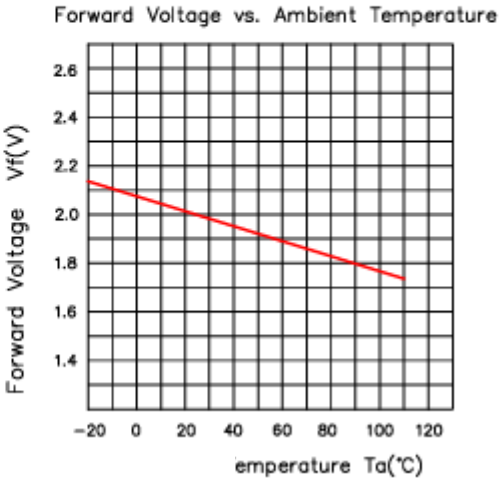
Typical Characteristic Curves - Red

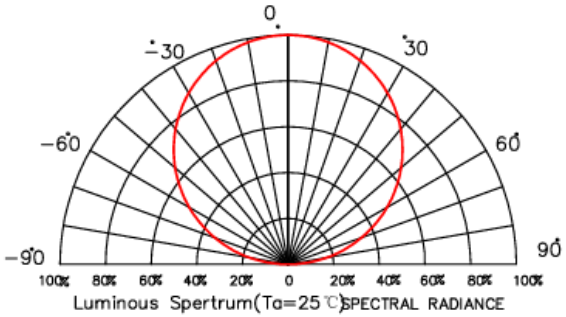






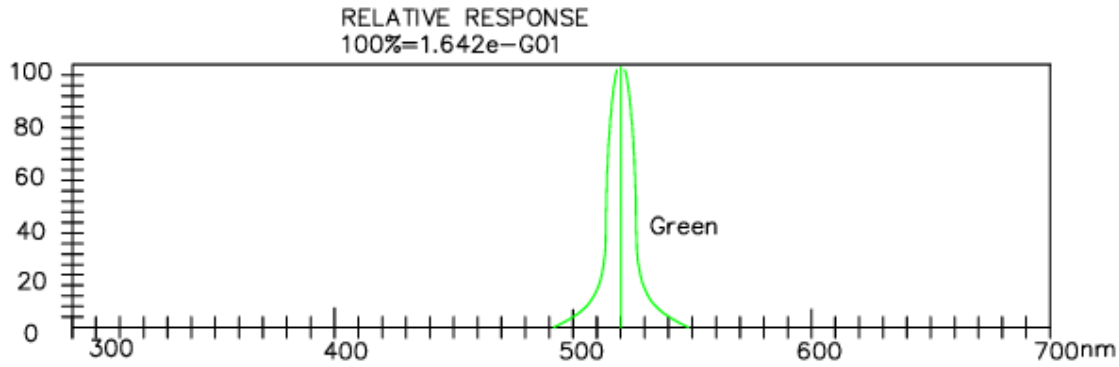




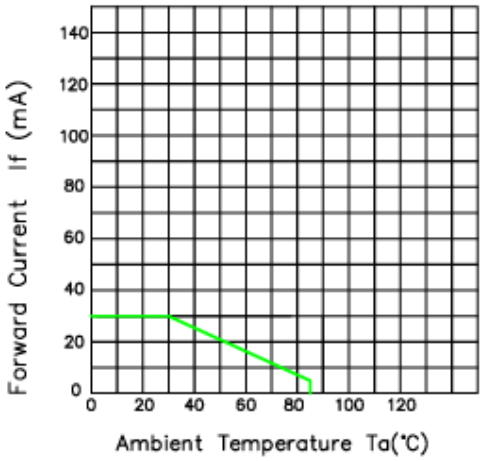


Typical **Characteristic**

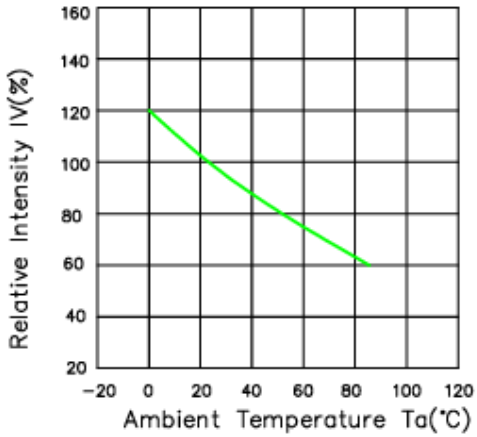
Curves - Green



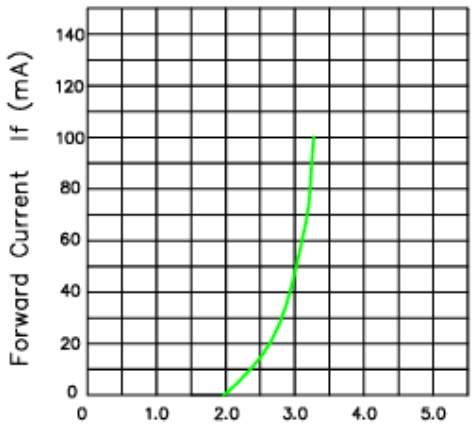
Forward Current vs. Ambient Temperature



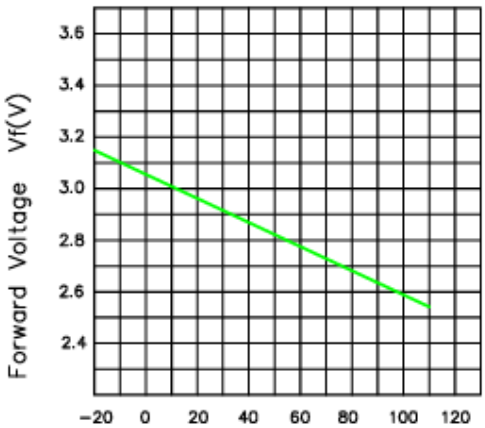
Relstive Intensity vs.Ambient Temperature

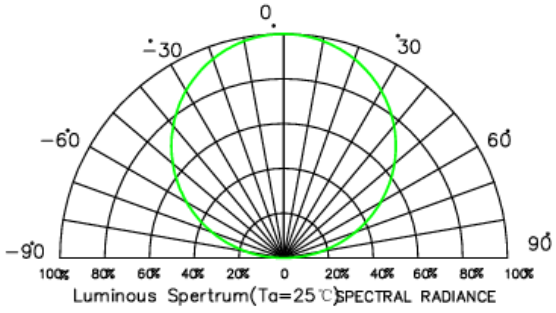


Forward Current vs. Forward Voltage

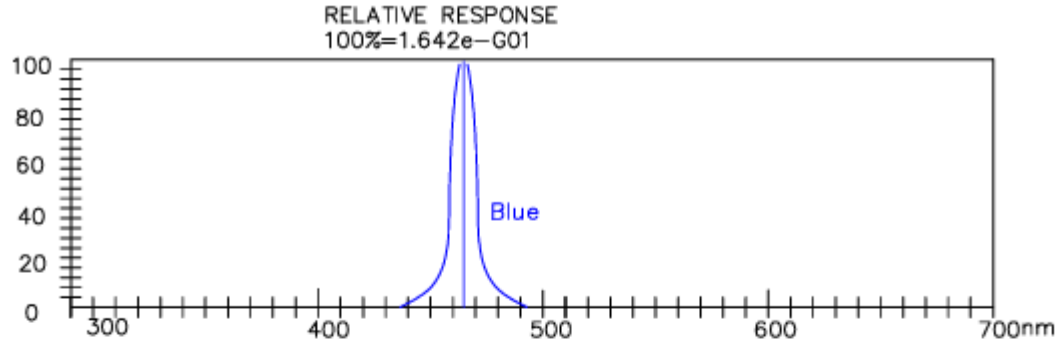


Forward Voltage vs. Ambient Temperature

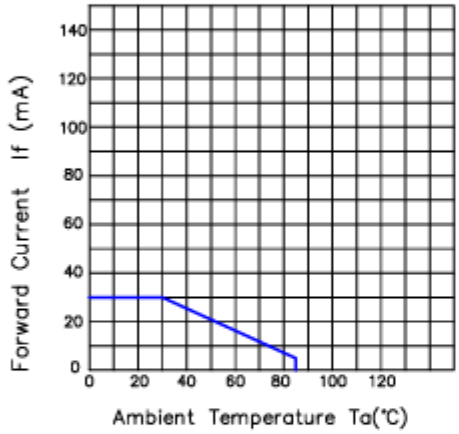




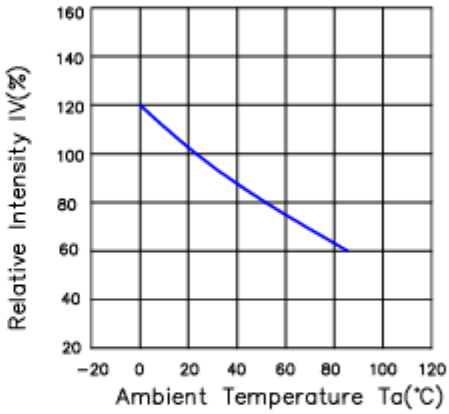
Typical Characteristic Curves - Blue



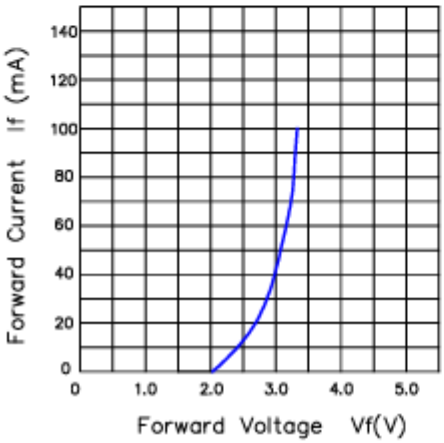
Forward Current vs. Ambient Temperature



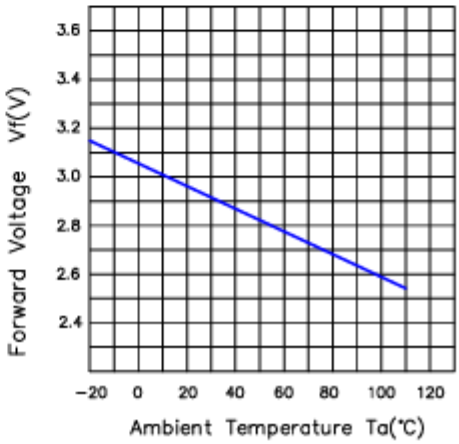
Relstive Intensity vs.Ambient Temperature

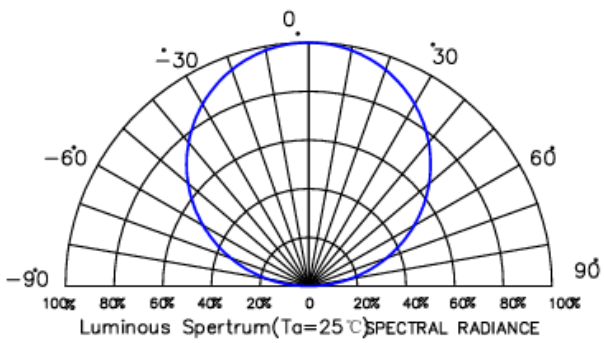


Forward Current vs. Forward Voltage



Forward Voltage vs. Ambient Temperature



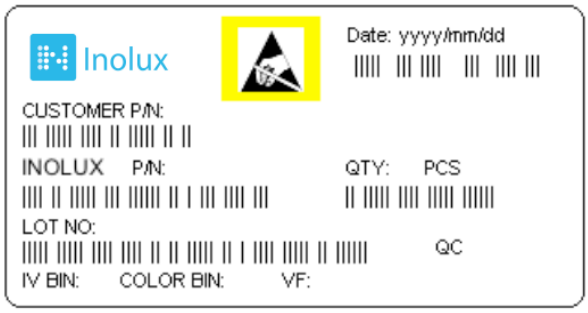


Ordering Information

Orderable Part Number	Emission Color	Technology	Test Current I_F (mA)	Luminous Intensity IV(mcd) (Typ.)	Forward Voltage V_F (V) (Typ.)
IN-P55TATRGB	Red	AlInGaP	20	900	2.2
	Green	InGaN	20	1800	3.2
	Blue	InGaN	20	600	3.2

- Bin Range specified on page 3.

Label Specifications



Inolux P/N:

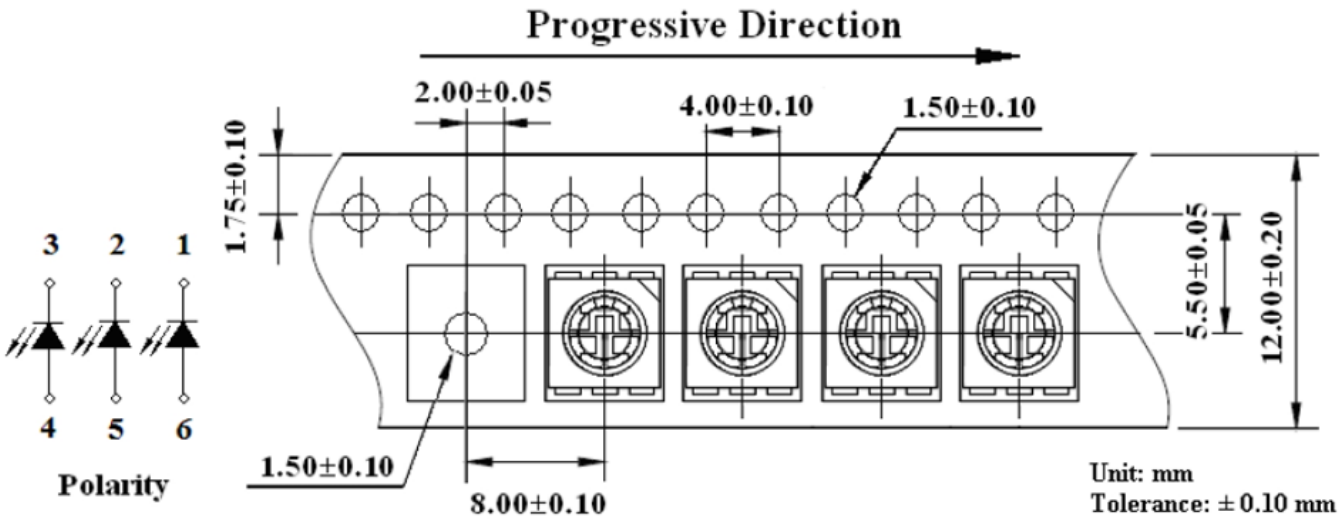
I	N	-	P	5	5	TA	T			R	G	B	-	-	-	-	-
Inolux SMD			Material	Package		Variation	Orientation	Current	Lens	Color				Customized Stamp-off			
			P = PLCC Type	55TA = 5.0 x 5.4 x 1.6 mm			T = Top Mount	(Blank) = 20mA per Chip	(Blank) = Clear	R=632nm G=520nm B=470nm				-			

Lot No.:

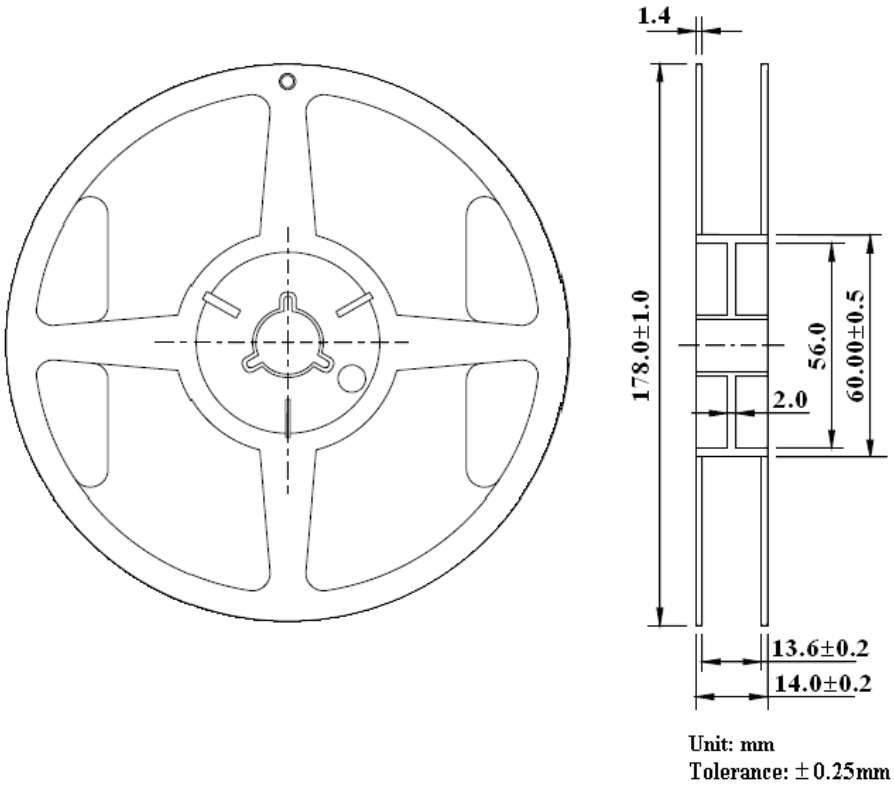
Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018, ...)				Month	Date	Serial

Packaging Information: 1000pcs Per Reel

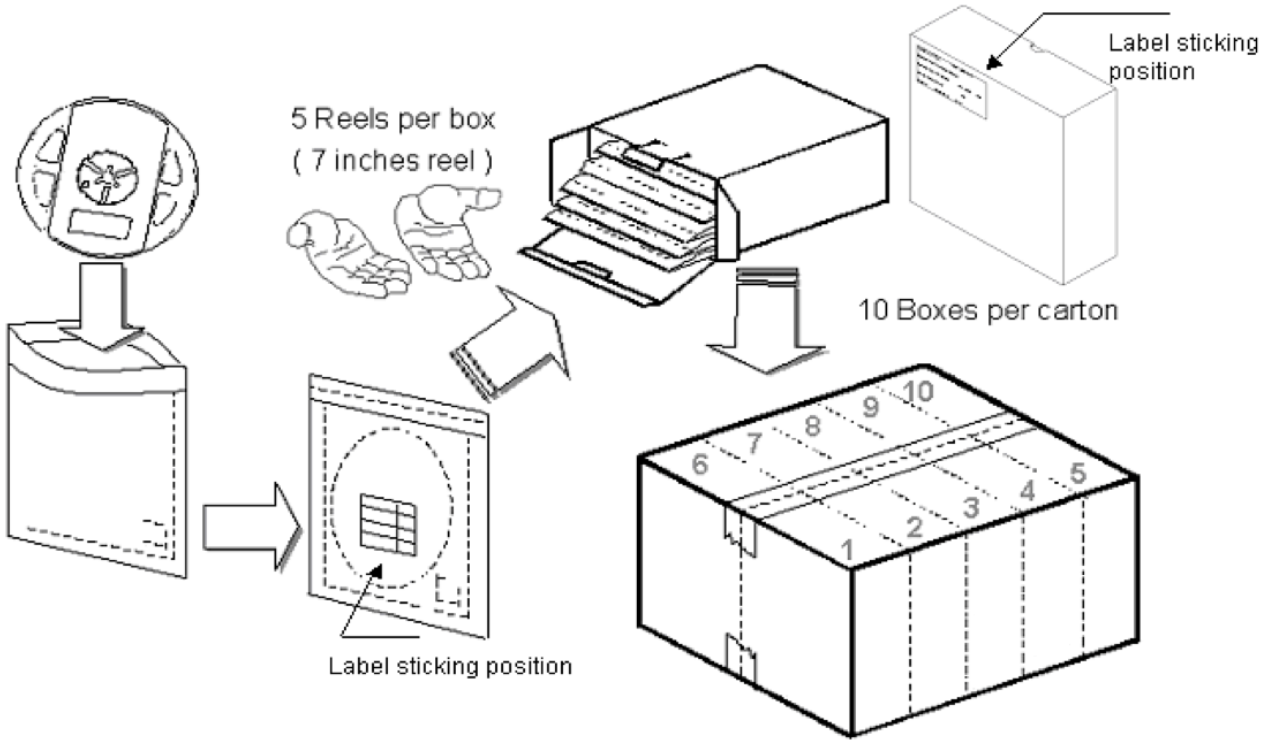
Tape Dimension



Reel Dimension



Packing Dimension



5 boxes per carton are available depending on shipment quantity.

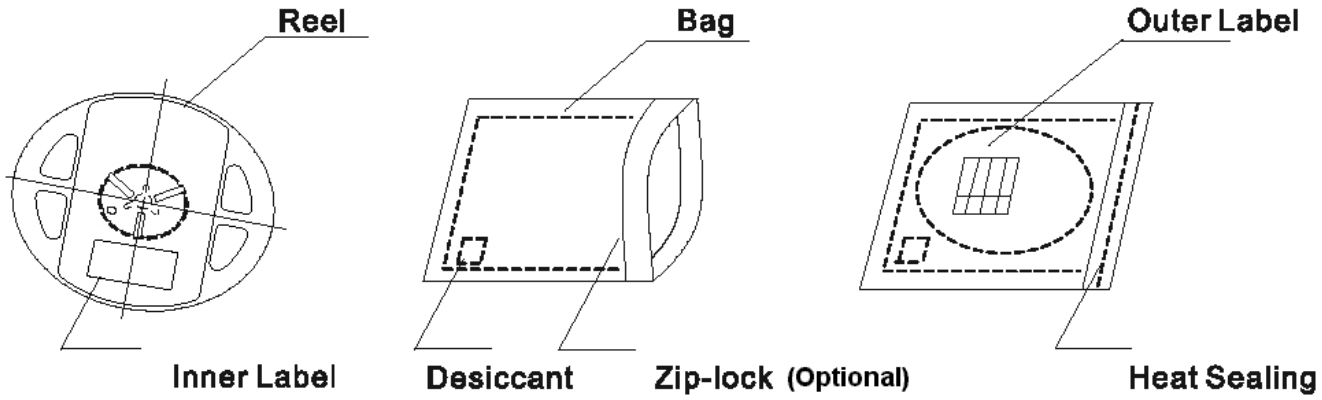
	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	1000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	Standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	Standard	Paper	Non-specified
Others: Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.			

Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

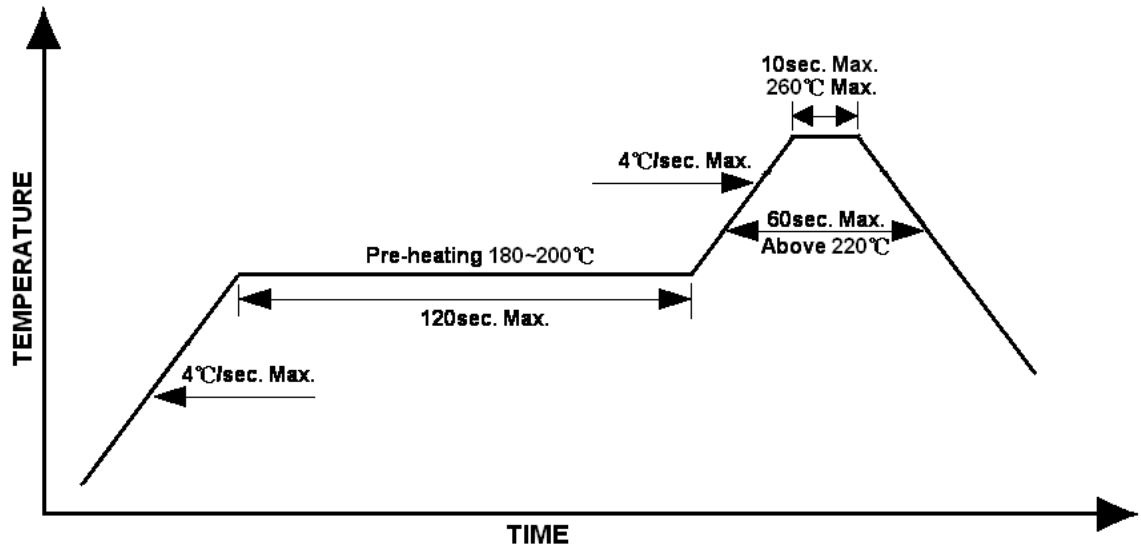
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192°C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260°C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100°C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	04-26-2017
Updated-(PCN NO: PCN IN 260815-01)		1.1	08-15-2026

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.